





N-CHANNEL ENHANCEMENT MODE MOSFET PLUS PNP TRANSISTOR

Features

- N-Channel MOSFET and PNP Transistor in One Package
- Low On-Resistance
- Very Low Gate Threshold Voltage, 1.0V max
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 2)
- ESD Protected MOSFET Gate up to 2kV
- "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

Case: SOT-363

Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0

Moisture Sensitivity: Level 1 per J-STD-020

Terminal Connections: See Diagram

Terminals: Finish - Matte Tin annealed over Alloy 42 lead frame. Solderable per MIL-STD-202, Method 208

Marking Information: See Page 5

Ordering Information: See Page 5

Weight: 0.006 grams (approximate)

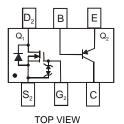
SOT-363







TOP VIEW



Internal Schematic

Maximum Ratings – MOSFET, Q1 @TA = 25°C unless otherwise specified

Characte	eristic	Symbol	Value	Units
Drain-Source Voltage		V_{DSS}	50	V
Gate-Source Voltage		V _{GSS}	±12	V
Drain Current (Note 1)	Continuous	I _D	160	mA
Pulsed Drain Current (Note 1)		I _{DM}	560	mA

Maximum Ratings - PNP Transistor, Q2 @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-50	V
Collector-Emitter Voltage	V _{CEO}	-45	V
Emitter-Base Voltage	V _{EBO}	-5.0	V
Collector Current	I _C	-100	mA

Thermal Characteristics, Total Device @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 1)	P _D	250	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ hetaJA}$	500	°C/W
Operating and Storage Temperature Range	T _{.I} , T _{STG}	-55 to +150	°C

Notes:

- 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- No purposefully added lead. Halogen and Antimony Free.
- 3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.



Electrical Characteristics - MOSFET @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 2)	-					
Drain-Source Breakdown Voltage	BV _{DSS}	50	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 50V$, $V_{GS} = 0V$
Gate-Body Leakage	I _{GSS}	_	_	1.0 5.0	μА	$V_{GS} = \pm 8V, V_{DS} = 0V$ $V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 2)						
Gate Threshold Voltage	$V_{GS(th)}$	0.7	0.8	1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Static Drain-Source On-Resistance		_	3.1	4	Ω	$V_{GS} = 4V, I_{D} = 100mA$
Static Drain-Source On-Resistance	R _{DS} (ON)	_	4	5		$V_{GS} = 2.5V, I_D = 80mA$
Forward Transconductance	g _{FS}	180	_	_	mS	$V_{DS} = 10V, I_D = 100mA,$ f = 1.0KHz
DYNAMIC CHARACTERISTICS						•
Input Capacitance	C _{iss}	_	25	_	pF	101/1/
Output Capacitance	Coss		5		pF	$V_{DS} = 10V, V_{GS} = 0V,$ - f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	2.1	_	pF	TI = 1.0IVII IZ

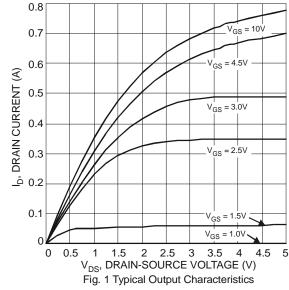
Electrical Characteristics - PNP Transistor @TA = 25°C unless otherwise specified

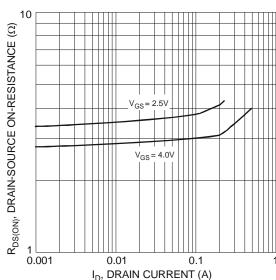
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage (Note 4)	V _{(BR)CBO}	-50	_		V	$I_C = 10\mu A, I_B = 0$
Collector-Emitter Breakdown Voltage (Note 4)	V _{(BR)CEO}	-45		—	V	$I_C = 10 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage (Note 4)	$V_{(BR)EBO}$	-5			V	$I_E = 1\mu A, I_C = 0$
DC Current Gain (Note 4)	h _{FE}	220	290	475	l	$V_{CE} = -5.0V, I_{C} = -2.0mA$
Collector-Emitter Saturation Voltage (Note 4)	V _{CE(SAT)}		1	-100	mV	$I_C = -10mA$, $I_B = -0.5mA$
Concetor Emitter Cataration Voltage (Note 4)	VCE(SAT)		_	-400	111 V	$I_C = -100 \text{mA}, I_B = -5.0 \text{mA}$
Base-Emitter Saturation Voltage (Note 4)	V _{BE(SAT)}	_	-700	_	mV	$I_C = -10 \text{mA}, I_B = -0.5 \text{mA}$
Date Emilier Galaration Voltage (1616-1)	VBE(SAT)		-900	_	111 V	$I_C = -100 \text{mA}, I_B = -5.0 \text{mA}$
Base-Emitter Voltage (Note 4)	V _{BE(ON)} -600		_	-750	mV	$V_{CE} = -5.0V, I_{C} = -2.0mA$
Base Emilier Voltage (Note 4)	VBE(ON)	_		-820	111 V	$V_{CE} = -5.0V, I_{C} = -10mA$
Collector-Cutoff Current (Note 4)	I _{CBO}	_	_	-15	nA	V _{CB} = -30V
Concetor Cutoff Current (Note 4)			1	-4.0	μA	$V_{CB} = -30V, T_A = 150^{\circ}C$
Collector-Emitter Cut-Off Current (Note 4)	I _{CES}	_		-100	nA	V _{CE} = -45V
Gain Bandwidth Product	f⊤	100	I	_	MHz	V _{CE} = -5.0V, I _C = -10mA, f = 100MHz
Output Capacitance	C _{OB}		I	4.5	рF	$V_{CB} = -10V, f = 1.0MHz$
Noise Figure	NF			10	dB	$I_C = -0.2 \text{mA}, V_{CE} = -5.0 \text{Vdc},$
Noise rigure	INF			10	ub	$R_S = 2.0K\Omega$, $f = 1.0KHz$, $BW = 200Hz$

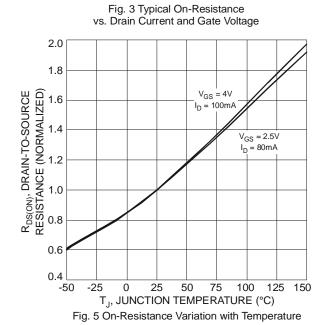
Notes: 4. Short duration pulse test used to minimize self-heating effect.

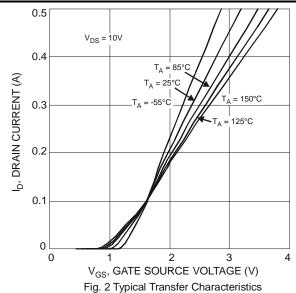


MOSFET









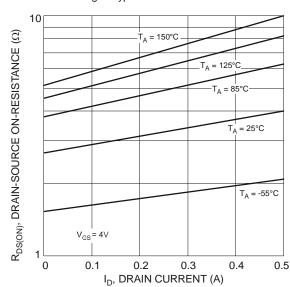
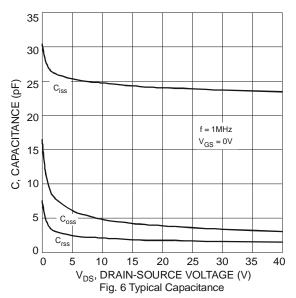


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature





MOSFET (continued)

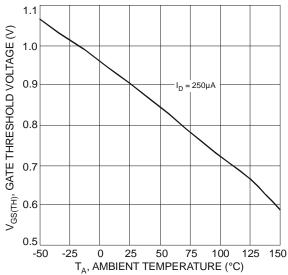


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

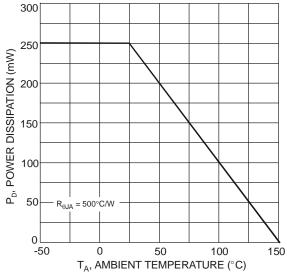
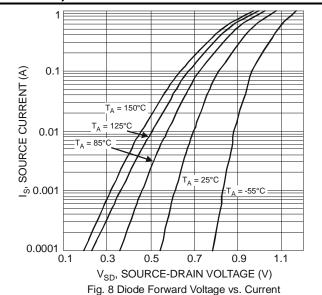
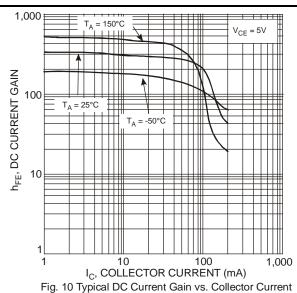


Fig. 9 Derating Curve - Total Package Power Dissipation





PNP Transistor



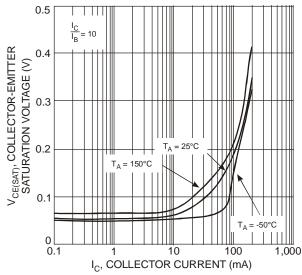


Fig. 11 Collector-Emitter Saturation Voltage vs. Collector Current

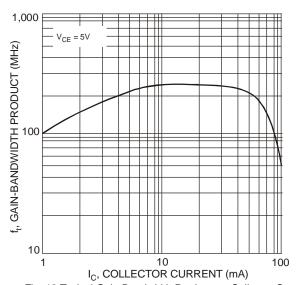


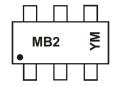
Fig. 12 Typical Gain-Bandwidth Product vs. Collector Current

Ordering Information (Note 5)

Part Number	Case	Packaging
DMB54D0UDW-7	SOT-363	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



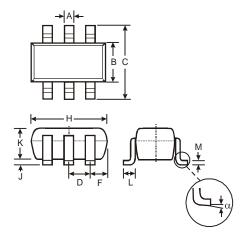
MB2 = Marking Code YM = Date Code Marking Y = Year (ex: V = 2008) M = Month (ex: 9 = September)

Date Code Key

Year	2008		2009	2010		2011	2012		2013	2014		2015
Code	V		W	X		Υ	Z		Α	В		С
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

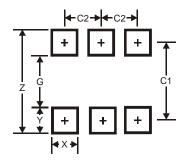


Package Outline Dimensions



	SOT-363					
Dim	Min	Max				
Α	0.10	0.30				
В	1.15	1.35				
С	2.00	2.20				
D	0.65	Тур				
F	0.40	0.45				
Н	1.80	2.20				
J	0	0.10				
K	0.90 1.00					
L	0.25 0.40					
М	0.10	0.22				
α	0°	8°				
All Di	All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65



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